



Appl. No. 10/672,886
Amdt. dated June 13, 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Sung Soon Park, et al.
Assignee: Amkor Technology, Inc.
Title: SEMICONDUCTOR PACKAGE STRUCTURE REDUCING WARPAGE
AND MANUFACTURING METHOD THEREOF
Serial No.: 10/672,886 Filed: September 26, 2003
Examiner: Nguyen, Tuan H. Group Art 2813
Docket No.: GK0017 Unit:
Monterey, CA

June 13, 2005

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312

Dear Sir:

Please amend the above-identified application as follows:

1. Amendments to the Specification begin on page 2 of this paper;
2. Amendments to the Claims are reflected in the listing of Claims which begins on page 4 of this paper;
3. Amendments to the Drawings begin on page 9 of this paper and include thirteen (13) attached replacement sheets (Appendix);
4. Remarks begin on page 11 of this paper; and
5. An Appendix follows page 11 of this paper.